

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Previously presented) A method comprising, providing electrical circuitry, subsequently moulding an electronic device cover member for an electronic device on to the electrical circuitry, and providing on the electronic device cover member an integral electrical connector structure for connecting the electrical circuitry to an electronic component, wherein the providing on the electronic device cover member an integral electrical connector structure comprises forming the integral electrical connector structure with the cover member in a mould, wherein the integral electrical connector structure is configured to removably receive at least a portion of a mating connecting member of the electronic component in the integral electrical connector structure.

2. (Previously presented) A method according to claim 1, wherein the moulding of the electronic device cover member on to the electrical circuitry comprises forming an electrical circuitry element, arranging the electrical circuitry element in the mould and moulding the cover member onto the electrical circuitry element.

3. (Previously presented) A method according to claim 2, wherein the moulding of the cover member comprises introducing

a plastics material into the mould after the electrical circuitry element is arranged in the mould.

4. (Previously presented) A method according to claim 3, wherein the plastics material is introduced into the mould by injection.

5. (Previously presented) A method according to claim 1, wherein the moulding of the electronic device cover member on to the electrical circuitry comprises forming a first part of the cover member in a first moulding operation, and forming a second part of the cover member in a second moulding operation, the second moulding operation comprising forming the electrical circuitry by forming a precursor for the electrical circuitry, and thereafter applying an electroconductive material to the precursor.

6. (Previously presented) A method according to claim 5, wherein the integral connector structure is formed on the second part during the second moulding operation.

7. (Previously presented) A method according to claim 5, wherein the first moulding operation comprises introducing a first plastics material into the first part of the mould.

8. (Previously presented) A method according to claim 5, wherein electroconductive material is a metallic material.

9. (Previously presented) A method according to claim 5, wherein the applying of the electroconductive material comprises plating the electroconductive material onto the precursor.

10. (Previously presented) A method according to claim 9, wherein the plating of the electroconductive material consists of one or both selected from electroplating and electroless plating.

11. (Previously presented) A method according to claim 9, wherein the second moulding operation comprises introducing a second plastics material into the mould, the second plastics material carrying a seeding substance to seed the plating of the electroconductive material onto the precursor, the seeding substance comprising metallic particles.

12. (Previously presented) A method according to claim 1, wherein the moulding of the electronic device cover member on to the electrical circuitry comprises providing a substrate, forming a precursor for the electrical circuitry on the substrate, moulding the substrate to form the cover member and then applying an electroconductive material to the precursor to form the electrical circuitry.

13. (Previously presented) A method according to claim 12, wherein the applying of the electroconductive material comprises plating the electroconductive material onto the precursor.

14. (Previously presented) A method according to claim 13, wherein the plating of the electroconductive material consists of one or both selected from electroplating and electroless plating.

15. (Previously presented) A method according to claim 13, wherein the forming of the precursor comprises applying a

carrier material to the substrate, the carrier material carrying a seeding substance to seed the plating of the electroconductive material onto the precursor, the secondary substance comprising metallic particles.

16. (Previously presented) A method according to claim 15, wherein the carrier material comprises an ink and the applying of the carrier material to the substrate comprises printing the carrier material on the substrate.

17. (Previously presented) A method according to claim 12, wherein the substrate comprises a plastics material and the moulding of the substrate to form the cover member comprises vacuum or press moulding the substrate.

18. (Previously presented) A method according to claim 12, wherein the providing of the connector structure on the cover member comprises moulding the connector onto the cover member after the substrate has been moulded to form the cover member.

19. (Previously presented) A method according to claim 1 comprising providing a flexible holding member in the connector structure to hold the electronic component in electrical communication with the electrical circuitry.

20. (Previously presented) A method according to claim 19, wherein the flexible holding member comprises a resilient member.

21-32. (Cancelled)

33. (Previously presented) A method comprising:

forming an electronic device cover member;

incorporating electrical circuitry into the cover member during the forming of the cover member; and

providing on the cover member an electrical connector structure for connecting the electrical circuitry to an electronic component, wherein the electrical connector structure is integrally formed with the cover member during the incorporating of the electrical circuitry into the cover member, wherein the electrical connector structure comprises an opening, wherein the opening forms an electrical connector receiving area, and wherein the electrical connector receiving area is configured to receive at least a portion of a connecting member of the electronic component therein.

34. (Previously presented) A method as in claim 1 wherein forming the electronic device cover member for an electronic device comprises forming a mobile phone cover member, wherein the electrical circuitry is incorporated into the mobile phone cover member during the formation of the mobile phone cover member, and wherein the mobile phone cover member comprises the integral connector structure.

35. (Previously presented) A method as in claim 33 wherein forming the electronic device cover member comprises forming a mobile phone cover member, wherein the mobile phone cover member is moulded on to the electrical circuitry, and wherein the connector structure is integrally formed with the mobile phone cover member.

36. (New) A method comprising, providing electrical circuitry, subsequently moulding an electronic device cover member for an electronic device on to the electrical circuitry, and providing on the electronic device cover member an integral connector, wherein the integral connector is configured to be connected to another connector to provide an electrical connection between the electronic device cover member and another member, wherein the providing on the electronic device cover member the integral connector comprises forming the integral connector with the cover member in a mould, and wherein the electrical circuitry is connected to the integral connector.